

S11 / S11 MMI

Repair Documentation

Level 2.5

V 1.2

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1 Introduction

The product family S1x consists of S10 (GSM-900), S11 (GSM-1800) and S12 (GSM-1900). The S10 is also available as a special outdoor version, the S10 Active. This phone has different display and RF/Control modules, even though many of the components are identical.

This manual is intended to help you carry out S11 repairs on level 2.5, meaning limited component repairs. Failure highlights are documented and should be repaired in the local workshops.

It must be noted that all repairs have to be carried out in an environment set up according to the ESD (Electrostatic Discharge Sensitive Devices) regulations defined in international standards.

If you have any questions regarding the repair procedures or spare parts do not hesitate to contact our technical support team in Kamp-Lintfort, Germany:

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2 Antenna Spring

2.1 Affected Units

2.1.1 Type: **S11**

2.1.2 Affected IMEIs / Date Codes: *All / All*

2.1.3 Affected SW-Versions: *All*

2.1.4 Fault Code for LSO reporting: **3ANS**

2.2 Fault Description

2.2.1 Fault Symptoms for customers:

Customers experience problems registering to the network and making calls.

2.2.2 Fault Symptom on GSM-Tester:

The GSM-Tester will show a low Tx-Power only on the *internal* antenna (aerial coupler measurement!).

2.3 Priority:

- Mandatory
- Repair
- Optional
- Not Yet Defined

2.4 Repair Documentation

2.4.1 Description of procedure:

2.4.1.1 Diagnosis

Visually check the status of the antenna spring. Look for a bent contact or dry soldering joint.

2.4.1.2 Repair by component change

Use soldering iron to remove defective spring.

Resolder new spring afterwards.

2.4.1.3 Repair by SW-Booting

Not possible!

2.4.1.4 Test

Retest handset after repair.

2.4.2 List of needed material

2.4.2.1 Components

Antenna Spring

Part-Number: L36158-A11-C23

2.4.2.2 Jigs and Tools

Soldering Iron

2.4.2.3 Special Tools

None

2.4.2.4 Working materials

Desolder Wick / Braid
Solder

2.4.3 Drawings

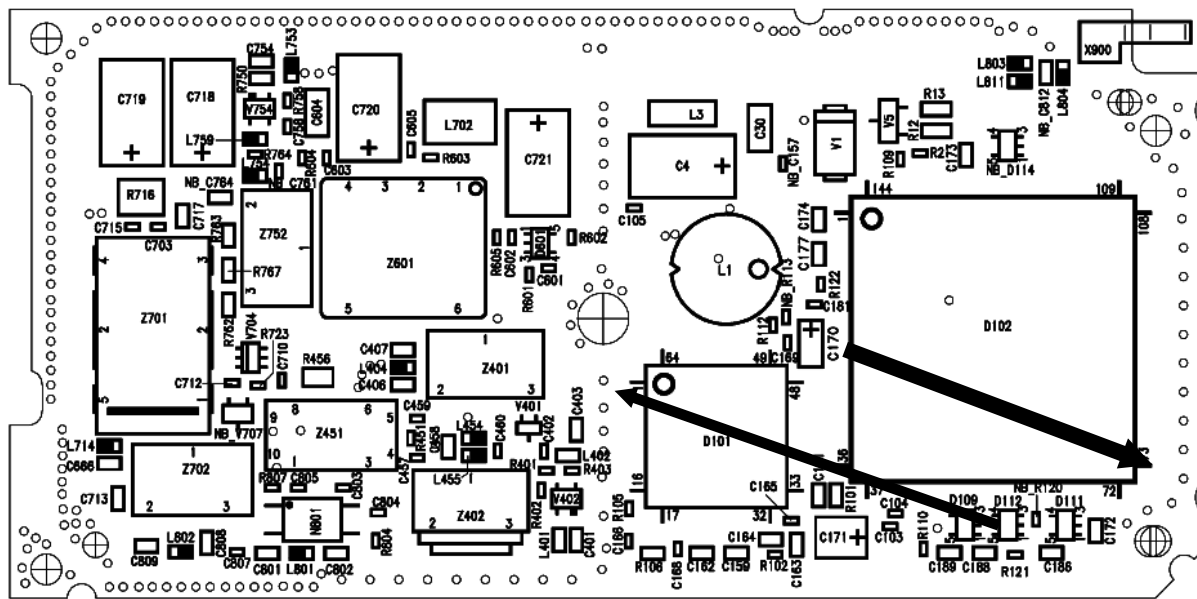
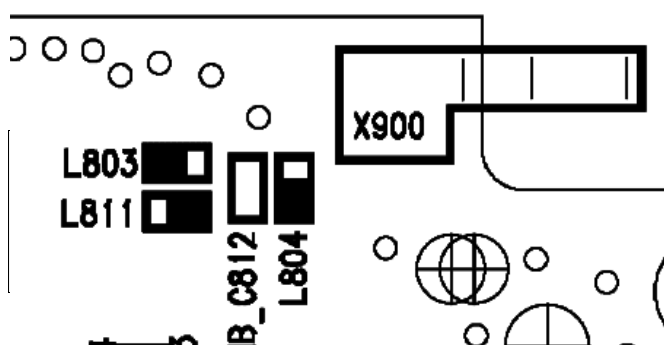


Figure 2: S11 Antenna Spring (X900) Placement (Top View)



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3TCXO

3.1 Affected Units

3.1.1 Type: S11

3.1.2 Affected IMEIs / Date Codes: All / All

3.1.3 Affected SW-Versions: All

3.1.4 Fault Code for LSO reporting: 3TCX

3.2 Fault Description

3.2.1 Fault Symptoms for customers:

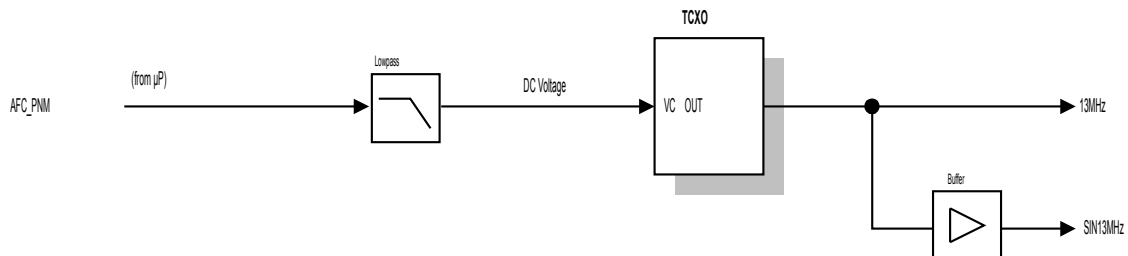
Network Search
Handset not logging into network

3.2.2 Fault Symptom on GSM-Tester:

Frequency error in synchronized mode >90 Hz
No location update possible

The TCXO (Temperature Compensated Crystal Oscillator) is responsible for generating the 13 MHz reference frequency of the handset.

If it is defective, the handset cannot synchronize to the base station anymore.



All other frequencies are derived from this 13MHz reference, its stability is vital for the handset function.

The TCXO output frequency is determined by a DC tuning voltage applied to its VC pin. The voltage comes from the microprocessor as a pulse number modulated digital signal. A lowpass then converts this digital signal to a proportional DC voltage, which is then used to fine tune the TCXO output frequency.

3.3 Priority:

- Mandatory
- Repair
- Optional
- Not Yet Defined

3.4 Repair Documentation

3.4.1 Description of procedure:

3.4.1.1 Diagnosis

Check the output frequency of the TCXO using the level-2 testing program for S11.
Switch off the „CMD in Use“ option in the config file (S6xx.CFG or S6xx.INI depending on the version of the testsoftware) and restart the program. Start the S11 test, when the program says „Check power and phase of external antenna with your GSM-Tester“, switch the CMD to „LOCAL“ mode and enter the „MODULE TEST“.
On the CMD display you can see the frequency error of the handset. (Make sure that the CMD is on channel number defined in the [PCN] section of the S6xx.ini, power level 0!)

If the frequency error is higher than 2kHz, the TCXO has to be replaced.

3.4.1.2 Repair by component change

Use hot air blower to remove defective TCXO.

Avoid excessive heat!
Watch surrounding components!

Resolder new TCXO afterwards.

3.4.1.3 Repair by SW-Booting

Not possible!

3.4.1.4 Test

Retest handset after repair as described above.
The frequency error must now be < 2kHz.

3.4.2 List of needed material

3.4.2.1 Components

TCXO
Part-Number: L36145-G300-Y17

3.4.2.2 Jigs and Tools

Hot Air Blower
Soldering Iron

3.4.2.3 Special Tools

None

3.4.2.4 Working materials

Desolder Wick / Braid
Solder

3.4.3 Drawings

Figure 1: S11 Board TCXO Side

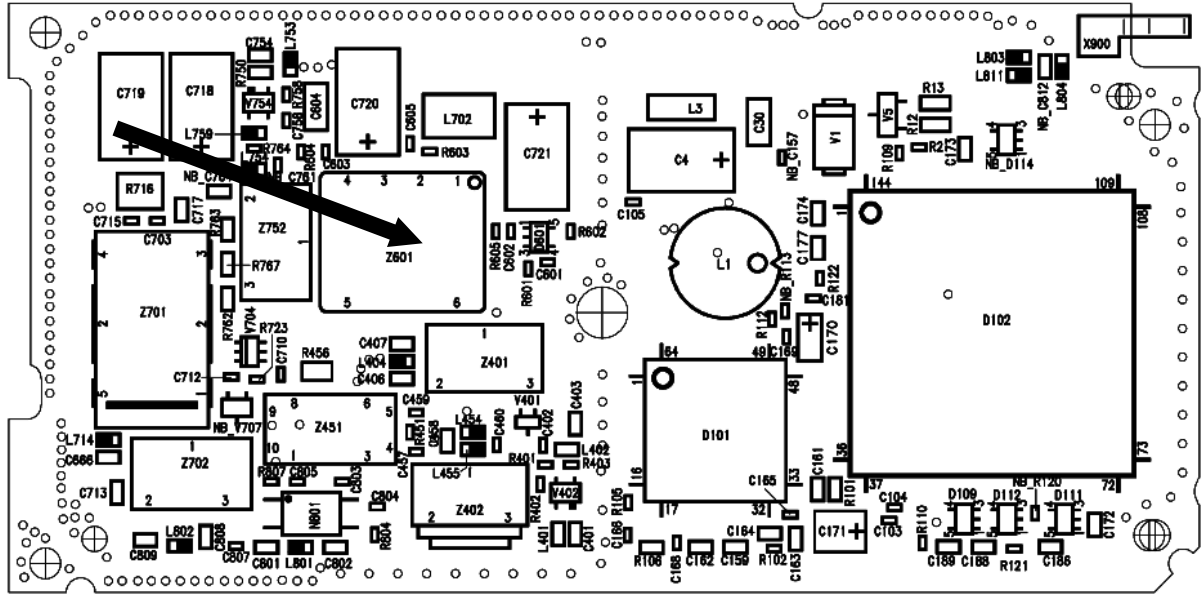
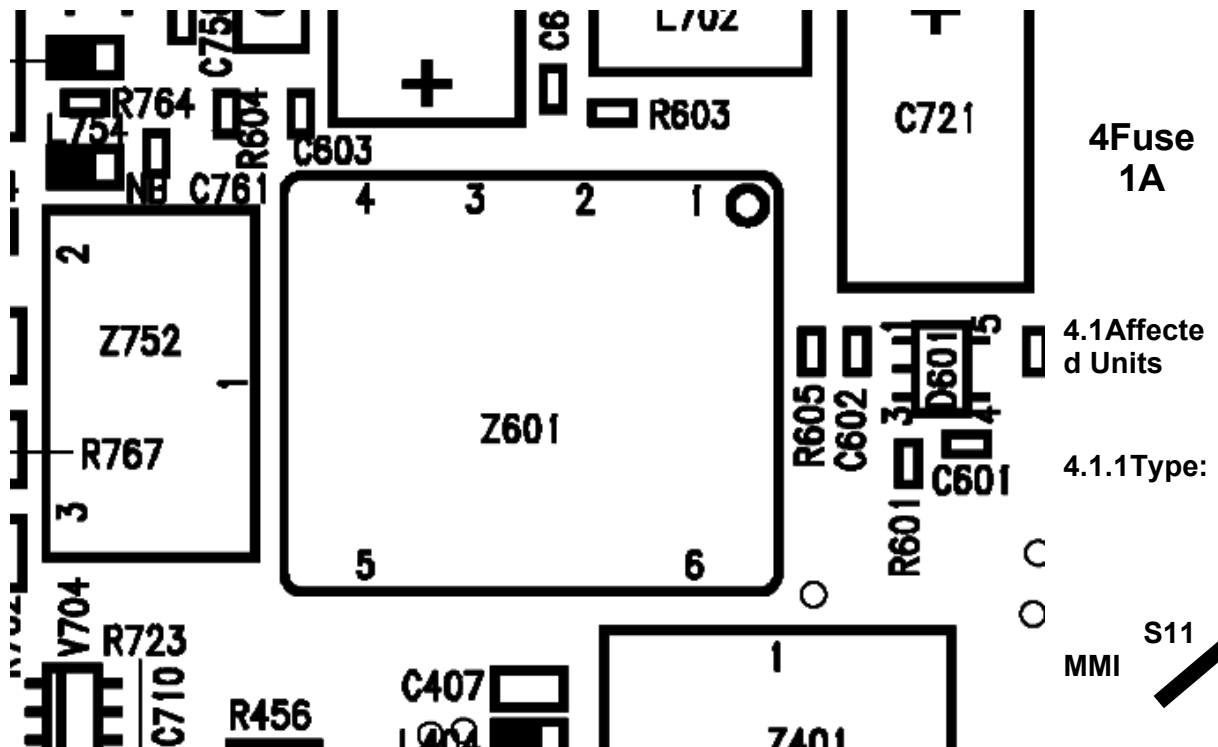


Figure 2: S11 TCXO (Z601) Placement (Top View)



4.1.2 Affected IMEIs / Date Codes: *All / All*

4.1.3 Affected SW-Versions: *All*

4.1.4 Fault Code for LSO reporting: 3FU1

4.2 Fault Description

4.2.1 Fault Symptoms for customers:

Battery charging not possible

4.2.2 Fault Symptom on GSM-Tester:

This fault cannot be detected with a GSM-Tester

4.3 Priority:

- Mandatory
- Repair
- Optional
- Not Yet Defined

4.4 Repair Documentation

4.4.1 Description of procedure:

4.4.1.1 Diagnosis

Check the status of the fuse by measuring its resistance with

a multimeter. The fuse is defective if the resistance higher than 10 ohms

4.4.1.2 Repair by component change

Use soldering iron to remove defective fuse.
Avoid excessive heat!
Watch surrounding components!

Resolder new fuse afterwards.

4.4.1.3 Repair by SW-Booting

Not possible!

4.4.1.4 Test

Retest handset after repair as described above.
The resistance must now be close to zero.

4.4.2 List of needed material

4.4.2.1 Components

Fuse

Part-Number: L36145-A820-Y7

4.4.2.2 Jigs and Tools

Soldering Iron

4.4.2.3 Special Tools

Multimeter

4.4.2.4 Working materials

Desolder Wick / Braid
Solder

4.4.3 Drawings

Figure 1: S11 MMI Board 1A Fuse Side

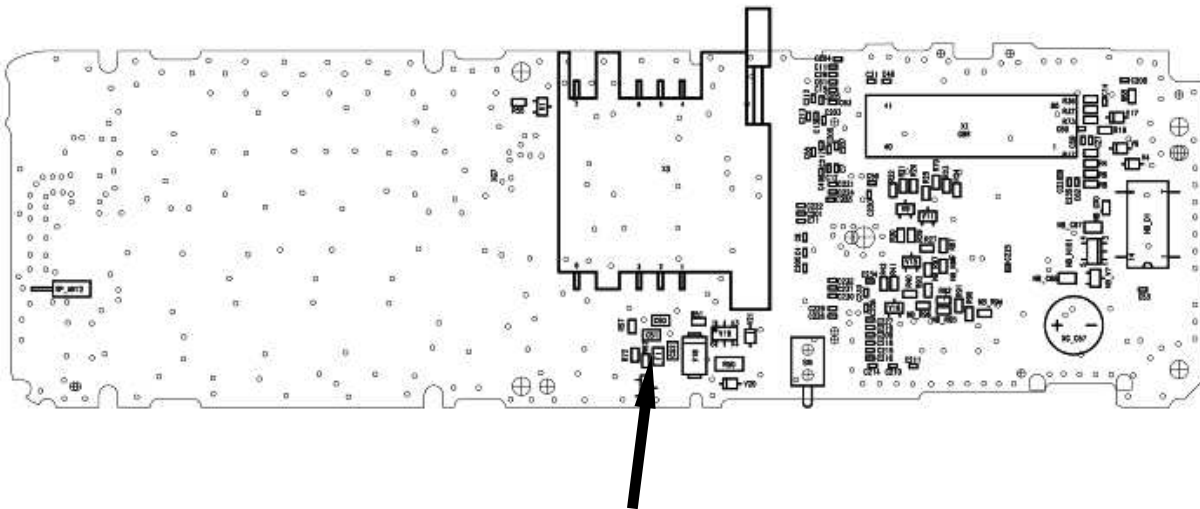
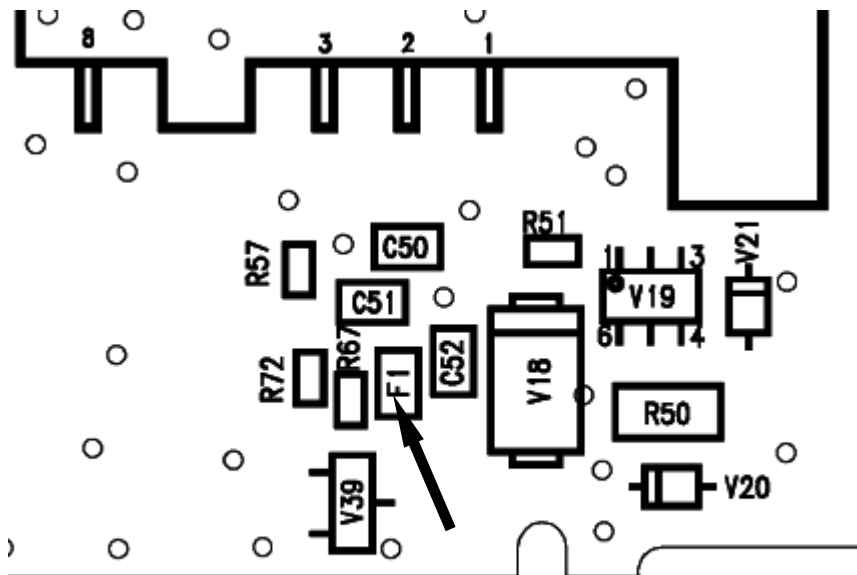


Figure 2: 1A Fuse (F1) Placement (Top View)



5Fuse 0.25 A

5.1 Affected Units**5.1.1 Type:** S11 MMI**5.1.2 Affected IMEIs / Date Codes:** *All / All***5.1.3 Affected SW-Versions:** *All***5.1.4 Fault Code for LSO reporting:** 3FU2**5.2 Fault Description****5.2.1 Fault Symptoms for customers:**

Supplying of external accessories through the handset's bottom connector is not possible

5.2.2 Fault Symptom on GSM-Tester:

This fault cannot be detected with a GSM-Tester

5.3 Priority:

- Mandatory
- Repair
- Optional
- Not Yet Defined

5.4 Repair Documentation**5.4.1 Description of procedure:****5.4.1.1 Diagnosis**

Check the status of the fuse by measuring its resistance with a multimeter. The fuse is defective if the resistance is higher than 10 ohms

5.4.1.2 Repair by component change

Use soldering iron to remove defective fuse.
Avoid excessive heat!
Watch surrounding components!

Resolder new fuse afterwards.

5.4.1.3 Repair by SW-Booting

Not possible!

5.4.1.4 Test

Retest handset after repair as described above.
The resistance must now be close to zero.

5.4.2 List of needed material**5.4.2.1 Components**

Fuse
Part-Number: L36145-A820-Y10

5.4.2.2 Jigs and Tools

Soldering Iron

5.4.2.3 Special Tools

Multimeter

5.4.2.4 Working materials

Desolder Wick / Braid
Solder

5.4.3 Drawings

Figure 1: S11 MMI Board 0.25A Fuse Side

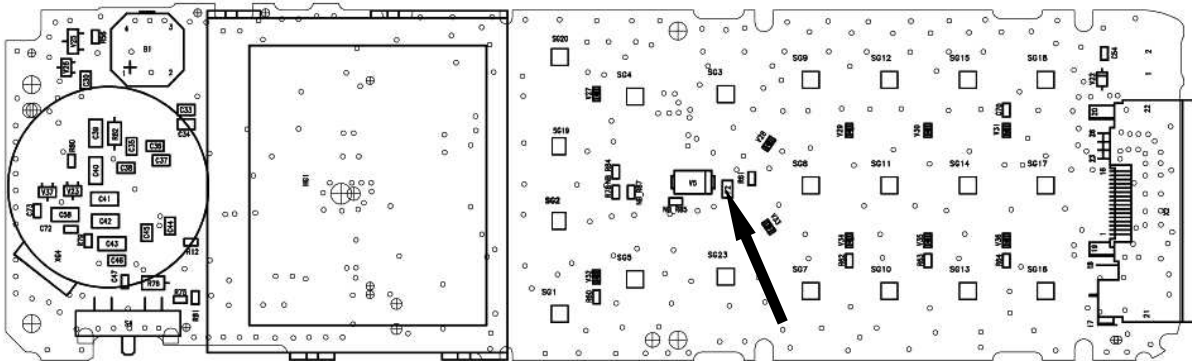
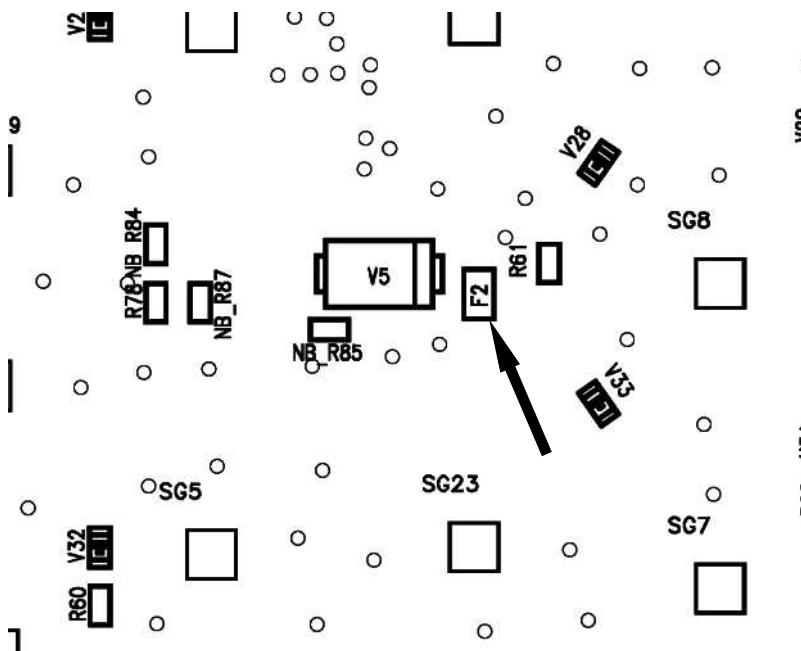


Figure 2: 0.25A Fuse (F2) Placement (Top View)



6Molex Connector

6.1 Affected Units

6.1.1 Type: **S11 MMI**

6.1.2 Affected IMEIs / Date Codes: *All / All*

6.1.3 Affected SW-Versions: *All*

6.1.4 Fault Code for LSO reporting: **3MOC**

6.2 Fault Description

6.2.1 Fault Symptoms for customers:

Charging or operation in a car kit not possible.

6.2.2 Fault Symptom on GSM-Tester:

Output power problems on the external antenna only.

6.3 Priority:

- Mandatory
- Repair
- Optional
- Not Yet Defined

6.4 Repair Documentation

6.4.1 Description of procedure:

6.4.1.1 Diagnosis

Visually check the bottom connector. Watch for dry joints.

6.4.1.2 Repair by component change

Use hot air blower to remove defective connector.
Avoid excessive heat!
Watch surrounding components!

Resolder new connector afterwards.
Make sure that you use just very little flux, otherwise the connector contacts can become dirty.

6.4.1.3 Repair by SW-Booting

Not possible!

6.4.1.4 Test

Retest handset after repair.

6.4.2 List of needed material**6.4.2.1 Components**

Molex Connector
Part-Number: L36334-Z93-C244

6.4.2.2 Jigs and Tools

Hot Air Blower
Soldering Iron

6.4.2.3 Special Tools

None

6.4.2.4 Working materials

Desolder Wick / Braid
Solder
Flux

6.4.3 Drawings

Figure 1: S11 MMI Board Bottom Connector Side

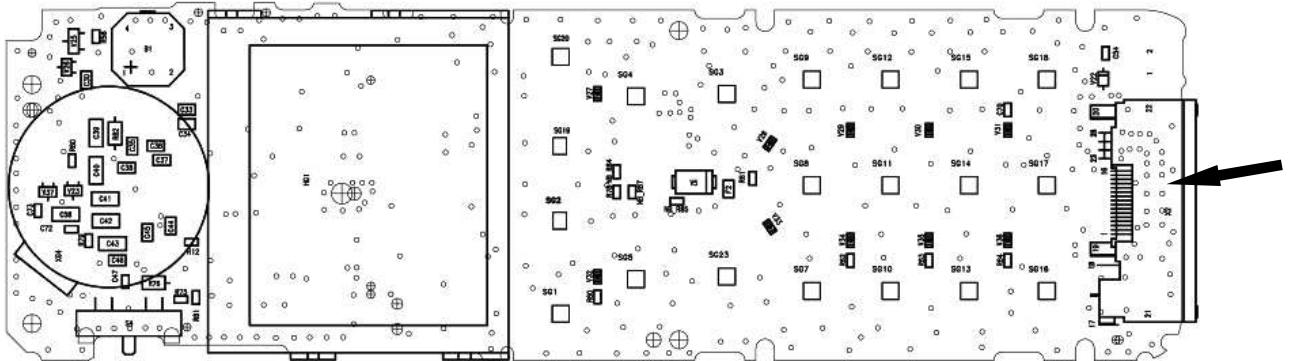
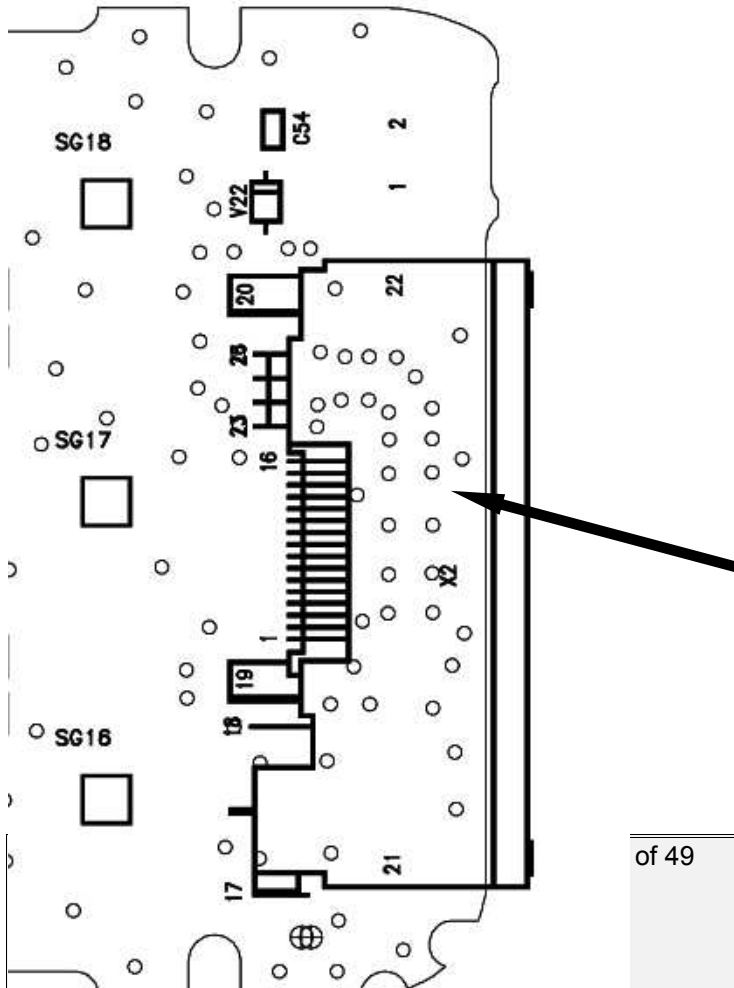


Figure 2: Bottom Connector Placement (Top View)



7Ringer

7.1 Affected Units

7.1.1 Type: **S11 MMI**

7.1.2 Affected IMEIs / Date Codes: *All / All*

7.1.3 Affected SW-Versions: *All*

7.1.4 Fault Code for LSO reporting: **3RIN**

7.2 Fault Description

7.2.1 Fault Symptoms for customers:

No ringer tone audible or ringer tone distorted.

7.2.2 Fault Symptom on GSM-Tester:

Ringer check fails.

7.3 Priority:

- Mandatory
- Repair
- Optional
- Not Yet Defined

7.4 Repair Documentation**7.4.1 Description of procedure:****7.4.1.1 Diagnosis**

Check ringer functionality either manually with testing program.

7.4.1.2 Repair by component change

Use hot air blower remove defective ringer.
Avoid excessive heat!
Watch surrounding components, especially the display window!
To protect the display, you can also desolder the ringer with solder wick.

Resolder new ringer afterwards.
Watch placement of ringer!

7.4.1.3 Repair by SW-Booting

Not possible!

7.4.1.4Test

Retest handset after repair.

7.4.2List of needed material**7.4.2.1Components**

Ringer
Part-Number: L36178-Z2-C15

7.4.2.2Jigs and Tools

Hot Air Blower
Soldering Iron

7.4.2.3Special Tools

None

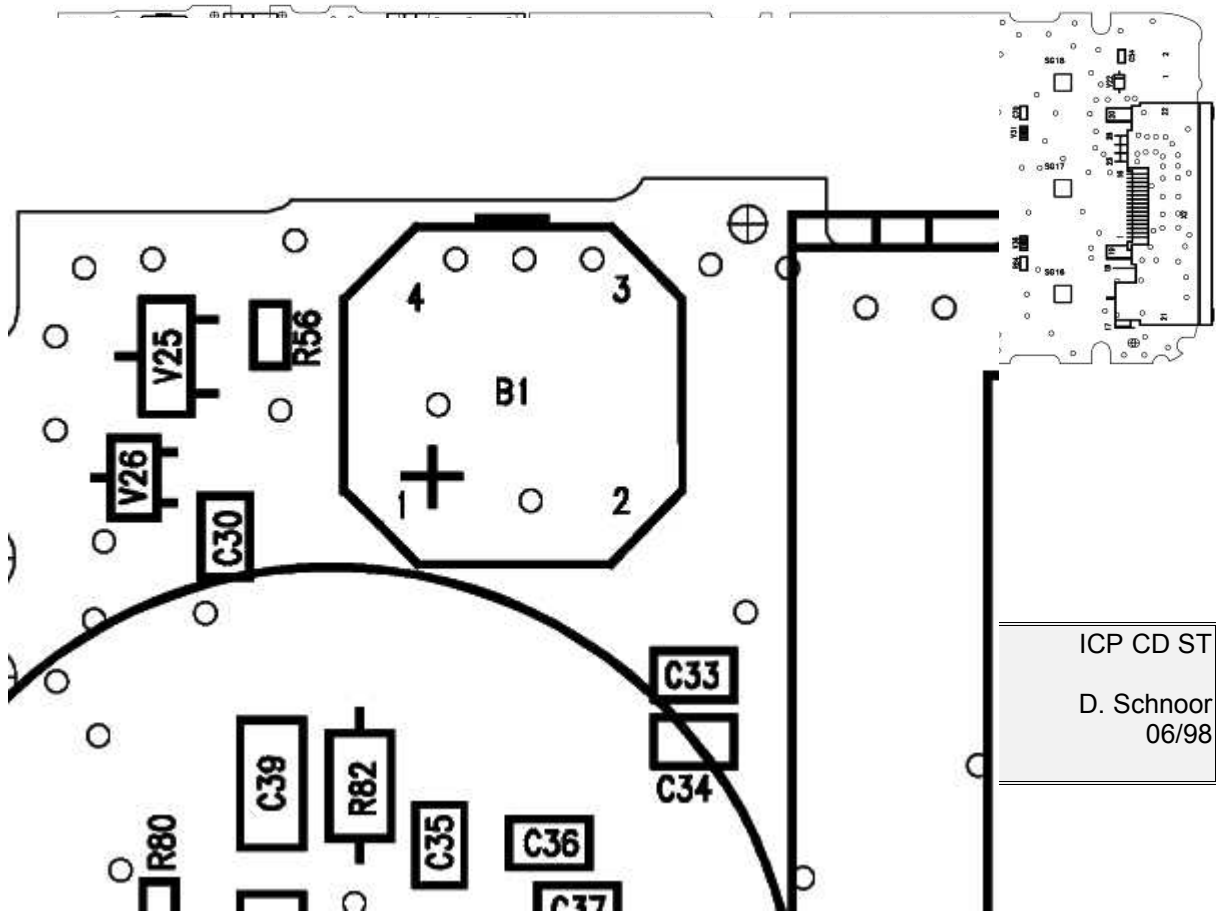
7.4.2.4Working materials

Desolder Wick / Braid

Solder

7.4.3 Drawings

Figure 1: S11 MMI Board Ringer Side



8Cardreader

8.1Affected Units

8.1.1Type: **S11 MMI**

8.1.2Affected IMEIs / Date Codes: *All / All*

8.1.3Affected SW-Versions: *All*

8.1.4Fault Code for LSO reporting: **3REA**

8.2Fault Description

8.2.1Fault Symptoms for customers:

Sim card is not accepted or properly read by
the handset.
Sim card ejection mechanism may be damaged.

8.2.2Fault Symptom on GSM-Tester:

When testing with a test-simcard the above symptoms will come up.

8.3 Priority:

- Mandatory
- Repair
- Optional
- Not Yet Defined

8.4 Repair Documentation**8.4.1 Description of procedure:****8.4.1.1 Diagnosis**

Check cardreader functionality with sim card.
Attention: Watch for dry joints (especially pin 7!) or mechanical damage.

8.4.1.2 Repair by component change

Resolder dry joints.

If the cardreader is mechanically damaged use solder wick to remove defective component.
Avoid excessive heat!
Watch surrounding components!!

Resolder new cardreader afterwards.

8.4.1.3 Repair by SW-Bootting

Not possible!

8.4.1.4 Test

Retest handset after repair.

8.4.2 List of needed material**8.4.2.1 Components**

Cardreader
Part-Number: L36334-Z95-C994

8.4.2.2 Jigs and Tools

Soldering Iron

8.4.2.3 Special Tools

None

8.4.2.4 Working materials

Desolder Wick / Braid
Solder

8.4.3 Drawings

Figure 1: S11 MMI Board Cardreader Side

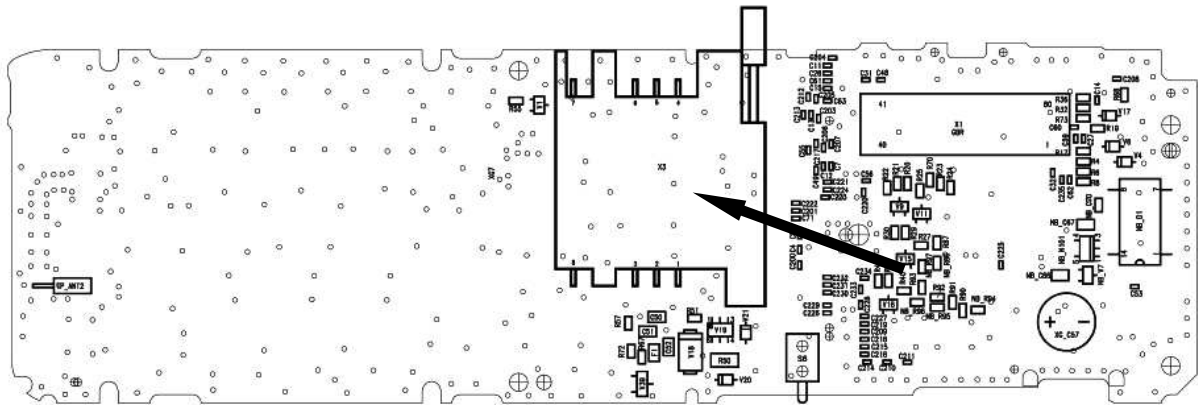
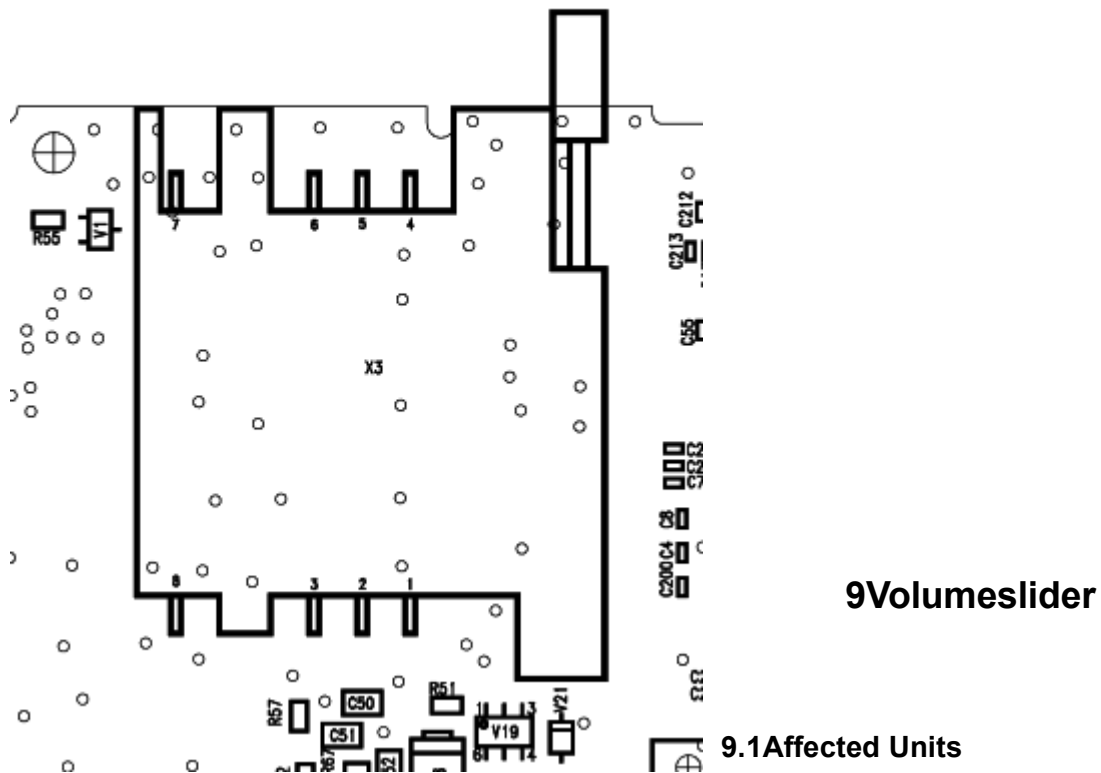


Figure 2: Cardreader Placement (Top View)



9.1.1 Type: S11 MMI

9.1.2 Affected IMEIs / Date Codes: All / All

9.1.3 Affected SW-Versions: *All*

9.1.4 Fault Code for LSO reporting: 3VSL

9.2 Fault Description

9.2.1 Fault Symptoms for customers:

The volume slider does not work properly.

9.2.2 Fault Symptom on GSM-Tester:

During the keyboard test, the volume slider fails.

9.3 Priority:

- Mandatory
- Repair
- Optional
- Not Yet Defined

9.4 Repair Documentation

9.4.1 Description of procedure:

9.4.1.1 Diagnosis

Check volumeslider functionality either manually or with the testing program.
Watch for dry joints or mechanical damage.

9.4.1.2 Repair by component change

Use solder wick to remove defective slider.
Avoid excessive heat!
Watch surrounding components!!

Resolder new volumeslider afterwards.

9.4.1.3 Repair by SW-Booting

Not possible!

9.4.1.4 Test

Retest handset after repair.

9.4.2 List of needed material**9.4.2.1 Components**

Volumeslider
Part-Number: L36315-Z77-C186

9.4.2.2 Jigs and Tools

Soldering Iron

9.4.2.3 Special Tools

None

9.4.2.4 Working materials

Desolder Wick / Braid
Solder

9.4.3 Drawings

Figure 1: S11 MMI Board Volumeslider Side

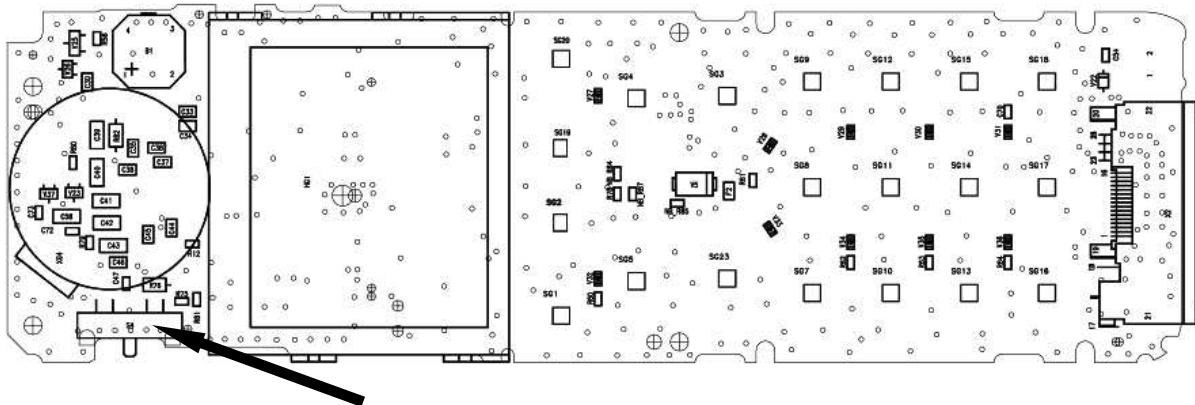
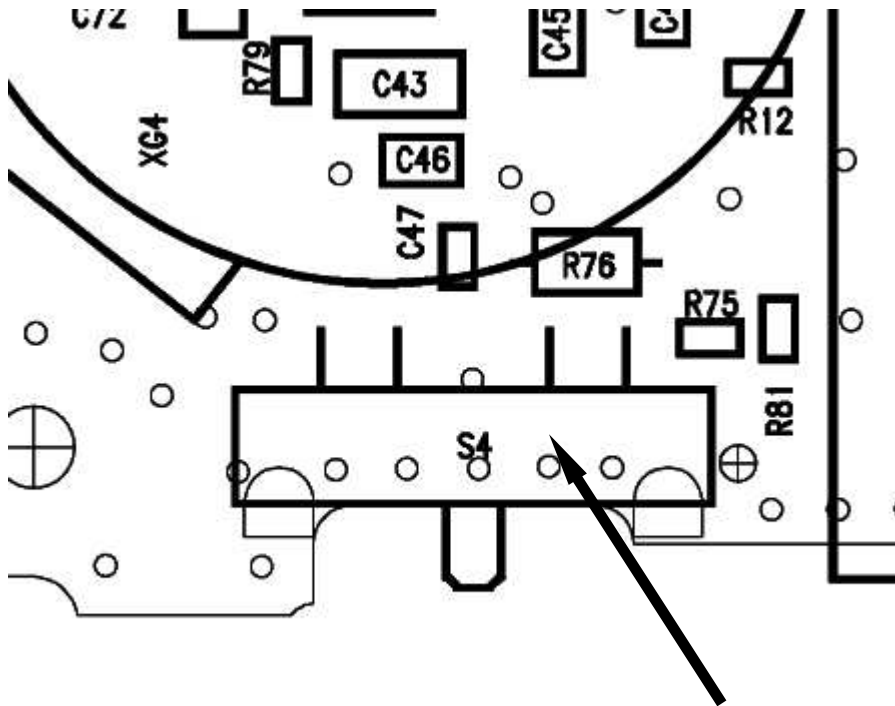


Figure 2: Volumeslider Placement (Top View)



10Memoswitch

10.1 Affected Units

10.1.1 Type: **S11 MMI**

10.1.2 Affected IMEIs / Date Codes: *All / All*

10.1.3 Affected SW-Versions: *All*

10.1.4 Fault Code for LSO reporting: **3MSW**

10.2 Fault Description

10.2.1 Fault Symptoms for customers:

The memoswitch does not work properly.

10.2.2 Fault Symptom on GSM-Tester:

During the keyboard test, the memobutton fails.

10.3 Priority:

- Mandatory
- Repair
- Optional
- Not Yet Defined

10.4 Repair Documentation

10.4.1 Description of procedure:

10.4.1.1 Diagnosis

Check memoswitch functionality either manually or with the testing program.

Watch for dry joints or mechanical damage.

10.4.1.2 Repair by component change

Use solder wick or hot air to remove defective switch.

Avoid excessive heat!

Watch surrounding components!!

Resolder new memoswitch afterwards.

10.4.1.3 Repair by SW-Booting

Not possible!

10.4.1.4 Test

Retest handset after repair.

10.4.2 List of needed material**10.4.2.1 Components**

Memoswitch
S11 Part-Number: L36315-Z77-C185

10.4.2.2 Jigs and Tools

Soldering Iron
Hot Air

10.4.2.3 Special Tools

None

10.4.2.4 Working materials

Desolder Wick / Braid
Solder

10.4.3 Drawings

Figure 1: S11 MMI Board Memoswitch Side

| | | |
|------|---------------|---------------------|
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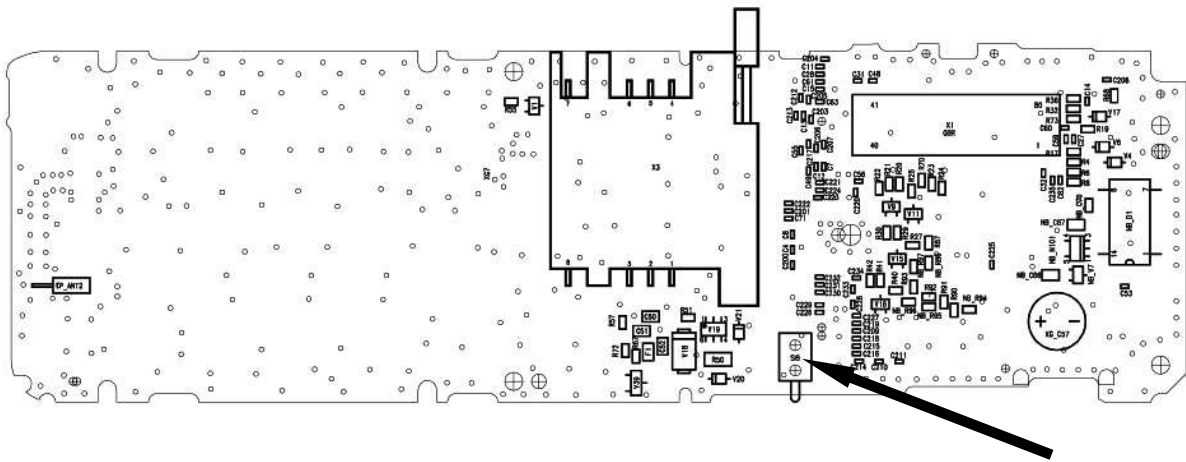
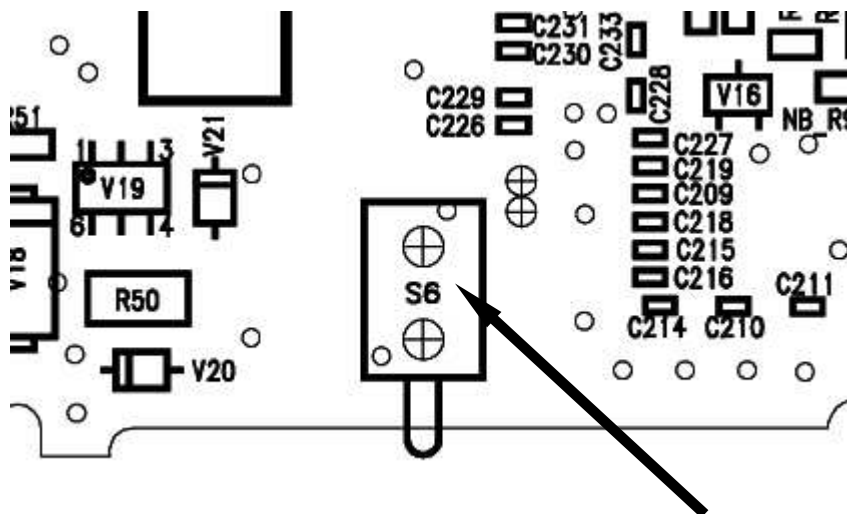


Figure 2: Memoswitch Placement (Top View)



11Antennaswitch

11.1 Affected Units**11.1.1 Type:** S11**11.1.2 Affected IMEIs / Date Codes:** All / All**11.1.3 Affected SW-Versions:** All**11.1.4 Fault Code for LSO reporting:** 3ASW**11.2 Fault Description****11.2.1 Fault Symptoms for customers:**

Problems with location update and call setup.
Network search.

11.2.2 Fault Symptom on GSM-Tester:

Handset fails with low Tx power on both or either
antenna.
No location update possible.

11.3 Priority:

- Mandatory
- Repair
- Optional
- Not Yet Defined

11.4 Repair Documentation**11.4.1 Description of procedure:**

11.4.1.1 Diagnosis

The antennaswitch is used to switch the Rx and Tx path between the internal an external antenna of the handset

The function of the antennaswitch can be verified by simple resistance measurements:

Pin 2 and 7 against ground must be around 86 kOhms.

If any of these resistances are significantly different, the antennaswitch will have to be replaced.

11.4.1.2 Repair by component change

Use solder wick or hot air to remove defective switch.
Avoid excessive heat!
Watch surrounding components!!

Resolder new antennaswitch afterwards.

11.4.1.3 Repair by SW-Booting

Not possible!

11.4.1.4 Test

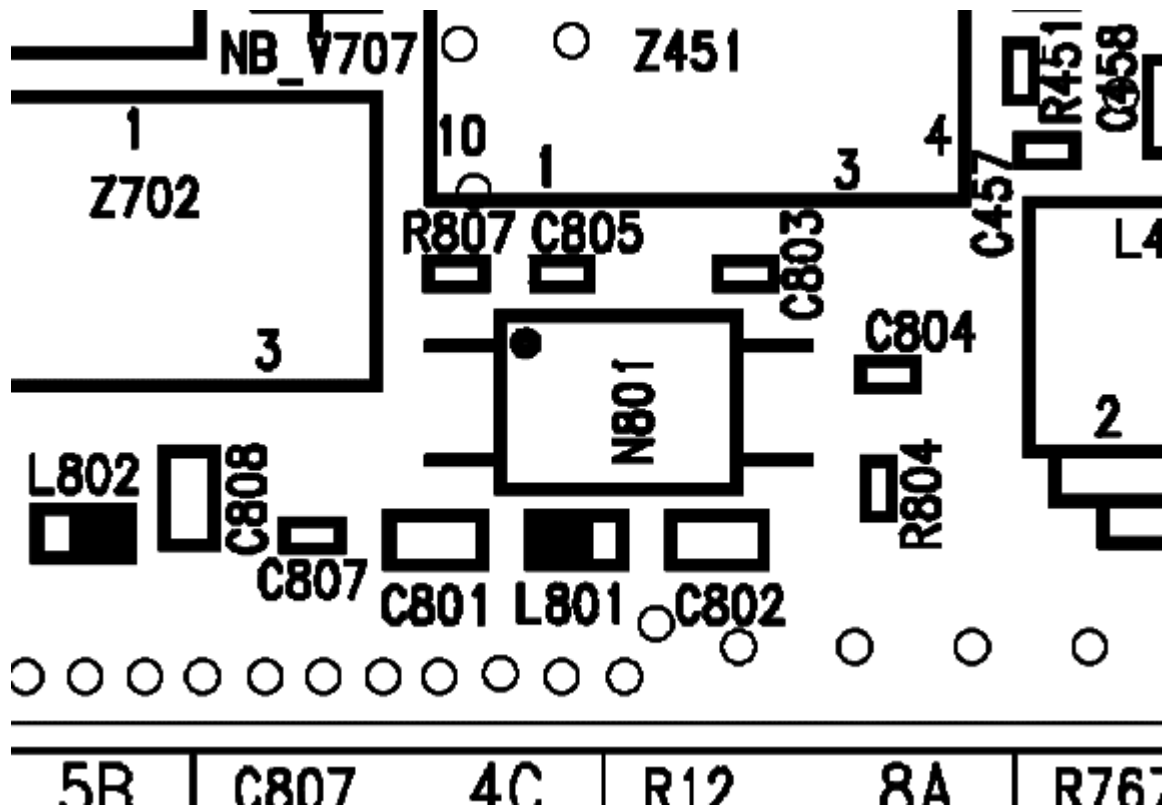
Retest handset after repair.

11.4.2 List of needed material**11.4.2.1 Components**

Antennaswitch
Part-Number: L36810-U6013-D670

11.4.2.2 Jigs and Tools

Soldering Iron



12Coil

12.1 Affected Units

12.1.1Type: **S11**

12.1.2Affected IMEIs / Date Codes: *All / All*

12.1.3Affected SW-Versions: *All*

12.1.4Fault Code for LSO reporting: 3COI

12.2Fault Description

12.2.1Fault Symptoms for customers:

Loud humming noise in loudspeaker.

12.2.2Fault Symptom on GSM-Tester:

Handset fails with loud humming noise in echo loop.

12.3Priority:

- Mandatory
- Repair
- Optional
- Not Yet Defined

12.4Repair Documentation

12.4.1 Description of procedure:**12.4.1.1 Diagnosis**

The coil is used in the step up converter which is generating a 6.0 V supply voltage for the power amplifier out of the 2.8V battery voltage.

If the coil is mechanically damaged (broken) it produces heavy interference with the acoustical elements of the S11 resulting in a loud humming noise in the earpiece.

A broken coil can easily be diagnosed by trying to move it with two fingers. If it moves, the core is broken and the coil has to be replaced.

12.4.1.2 Repair by component change

Use hot air to remove defective coil.
Avoid excessive heat!
Watch surrounding components!!

Resolder new coil afterwards

12.4.1.3 Repair by SW-Booting

Not possible!

12.4.1.4 Test

Retest handset after repair, by checking the audio quality with the echo loop of the testprogram.

12.4.2 List of needed material

12.4.2.1 Components

Part-Number: L36151-F5273-M2

12.4.2.2 Jigs and Tools

Soldering Iron
Hot Air Blower

12.4.2.3 Special Tools

None

12.4.2.4 Working materials

Desolder Wick / Braid
Solder

12.4.3 Drawings

Figure 1: S11 Board Coil (L1) Side

